Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

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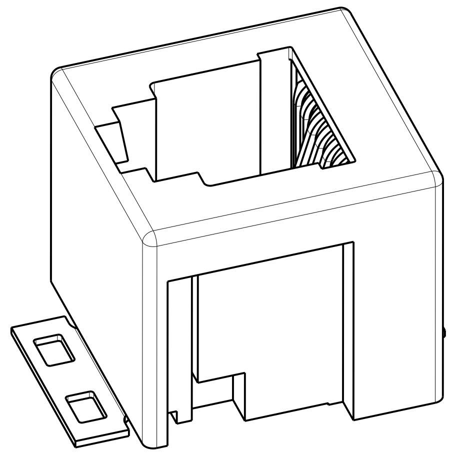
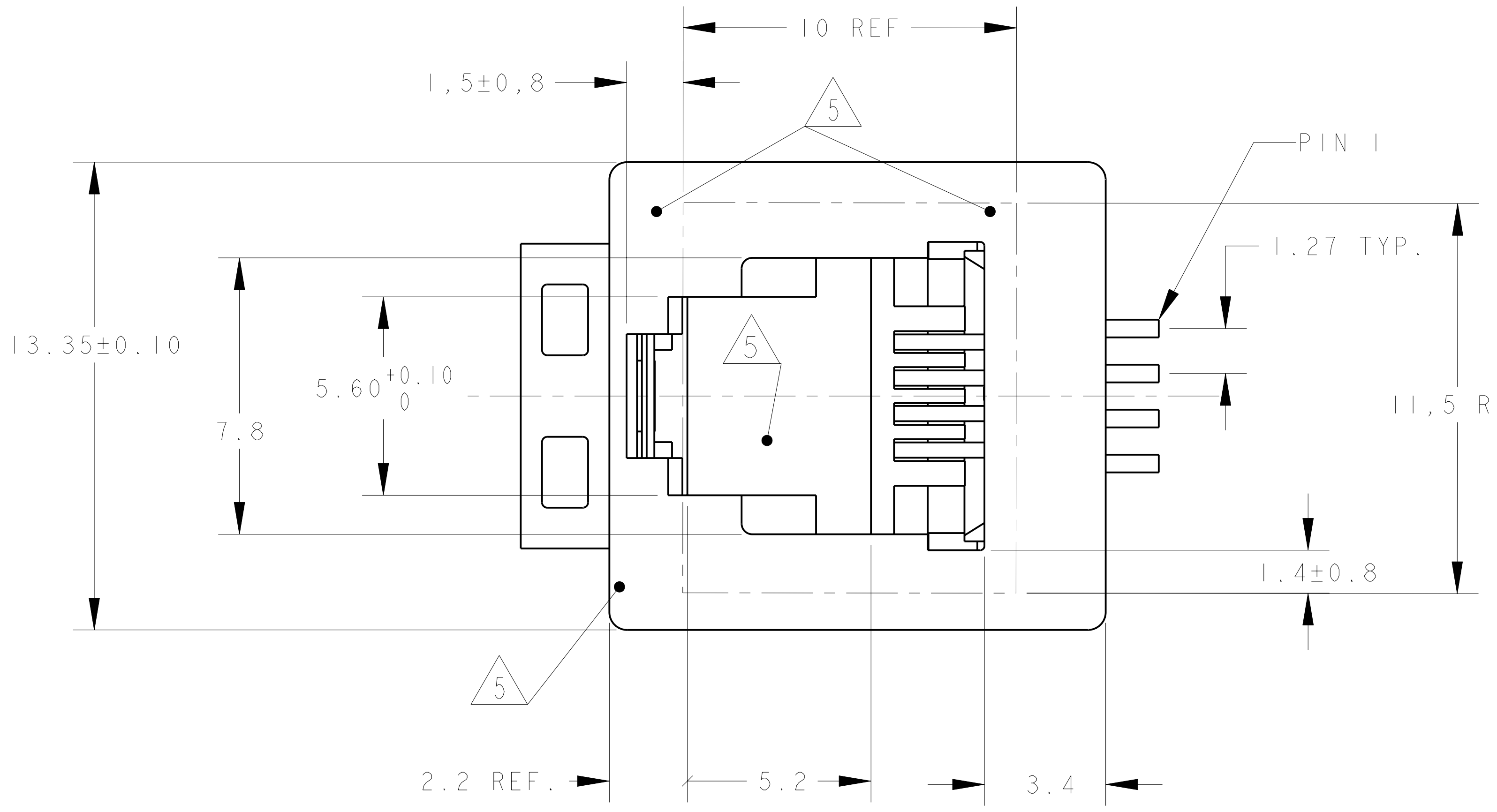
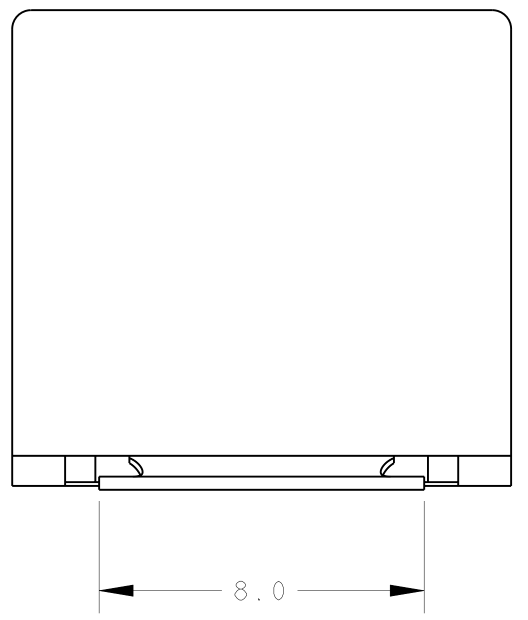
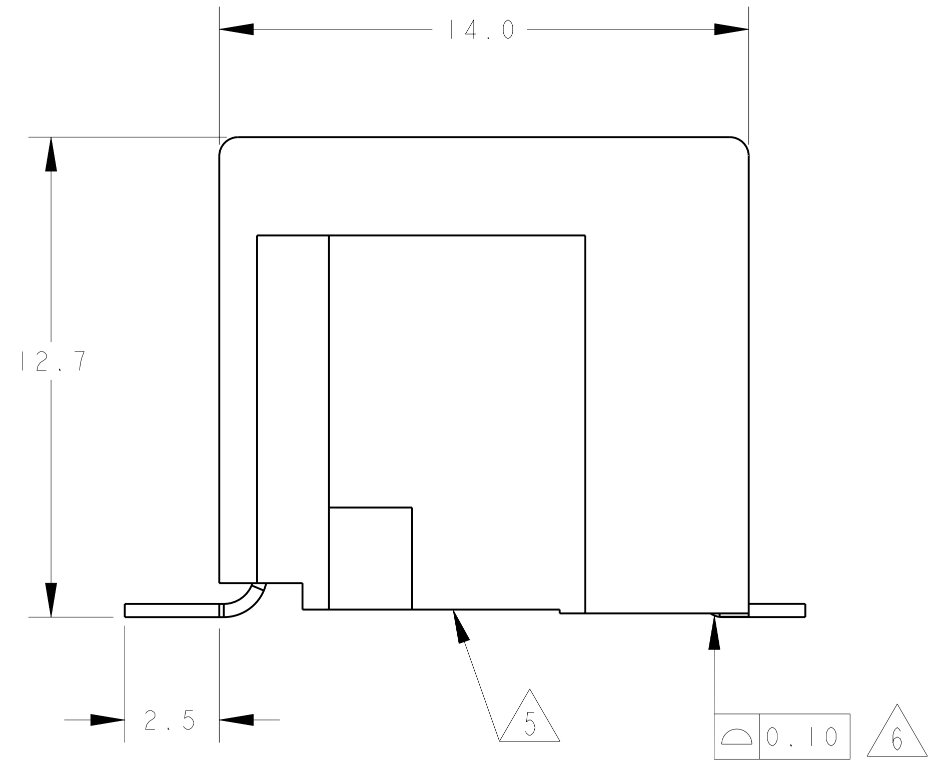
LOC	DIST
-	-

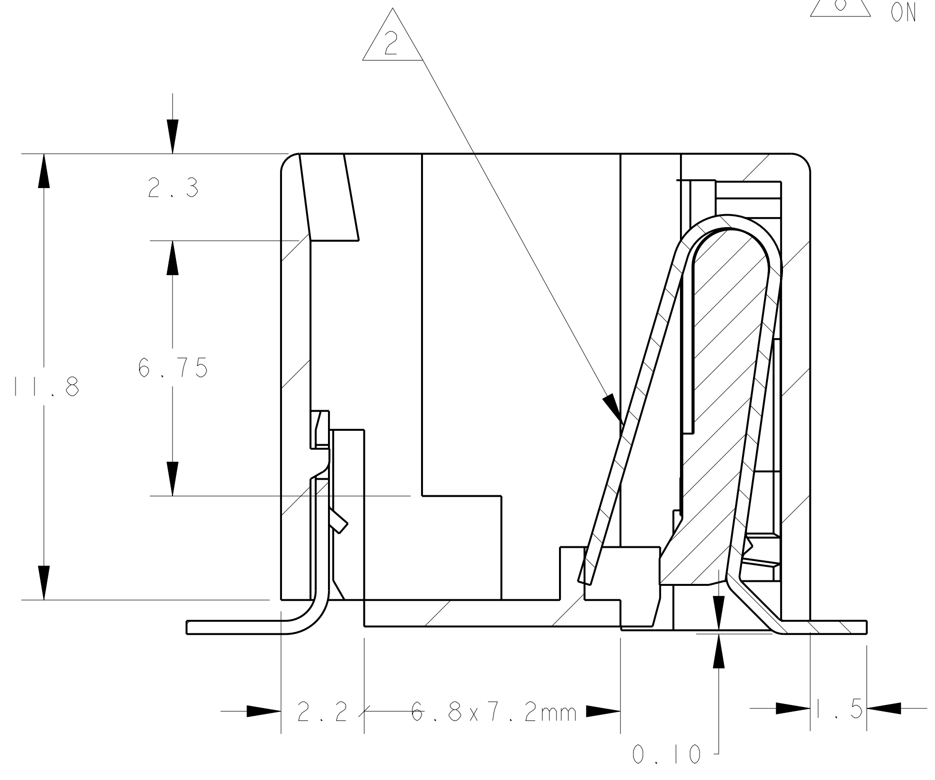
REVISIONS					
P	LTR	DESCRIPTION	DATE	DWN	APVD
	C	ECR-10-020218	21JUN2011	PS	RRP



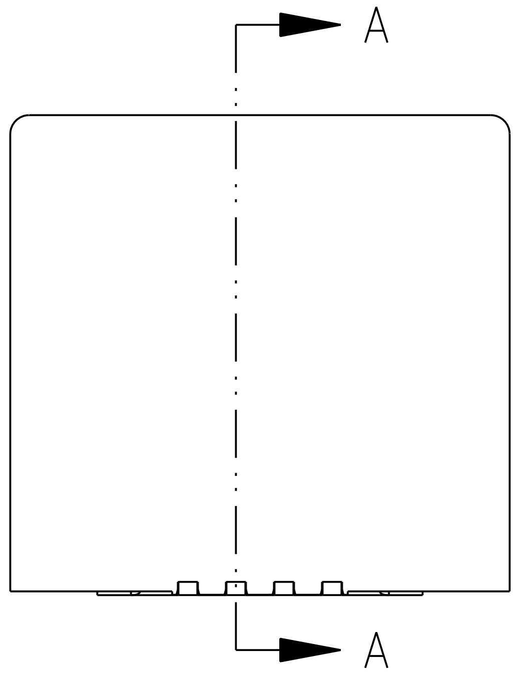








SECTION A-A



NOTES:

1 TOLERANCES UNLESS OTHERWISE SPECIFIED: ±0.15.

2 CONTACT PLATING:
OVERALL: Ni 1.27μm MIN. ALL OVER THE CONTACTS
SOLDER ZONE: Sn 3.5-5.0μm ON THE SOLDER ZONE OF THE CONTACT
MATING ZONE: PLATING CONFIRMS TO PRODUCT REQUIREMENTS AS PER SPECIFICATION 108-19117

3 MATERIALS:
HOUSING: 30% G.F. PA 9T COLOR BLACK, UL 94V-0.
CONTACTS: PHOSPHOR BRONZE
SOLDER BRACKET: TIN PLATED BRASS WITH NICKEL UNDERPLATE.

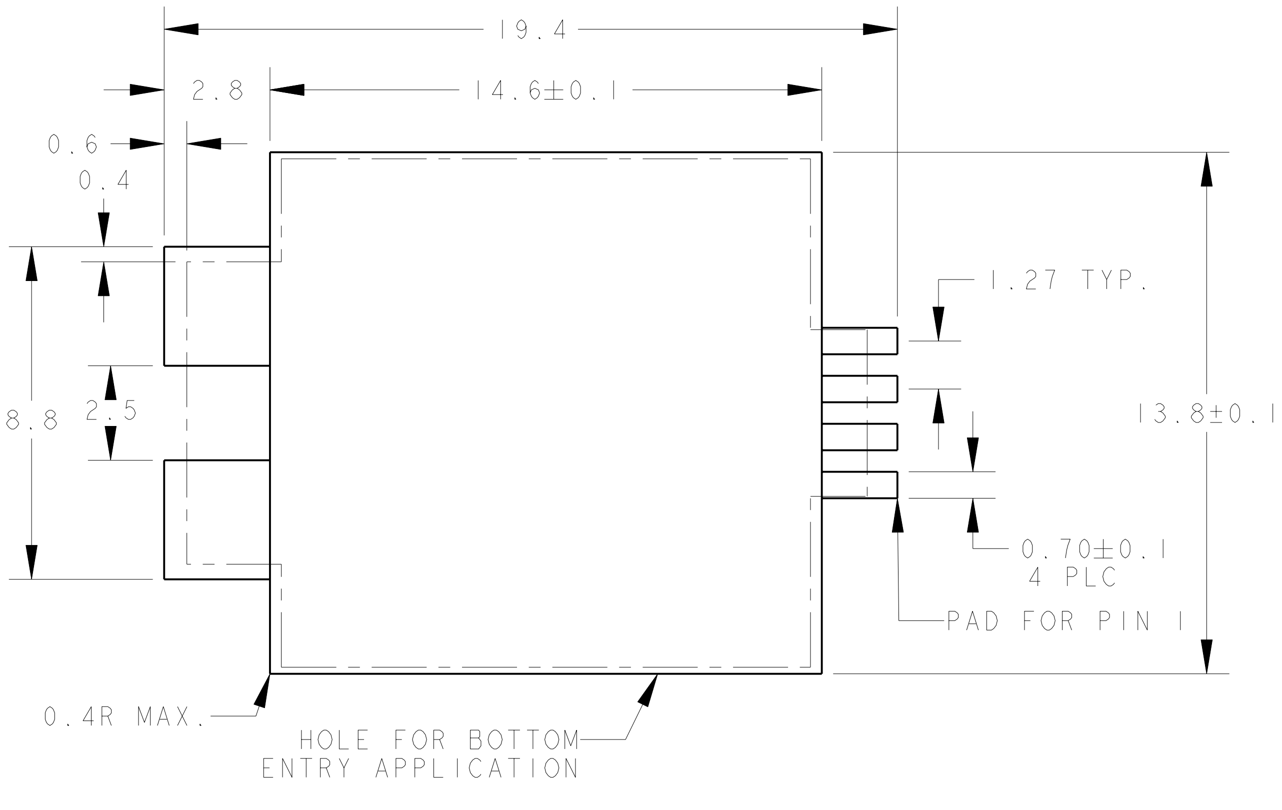
4 THIS JACK CAN ALSO BE APPLIED HANGING THROUGH A HOLE, IN A PRINTED CIRCUIT BOARD. SEE LEFT PCB LAYOUT.

5 SURFACE CAN BE USED FOR PICKING THE MODULAR JACK WITH, TYPE II SMD MACHINE.

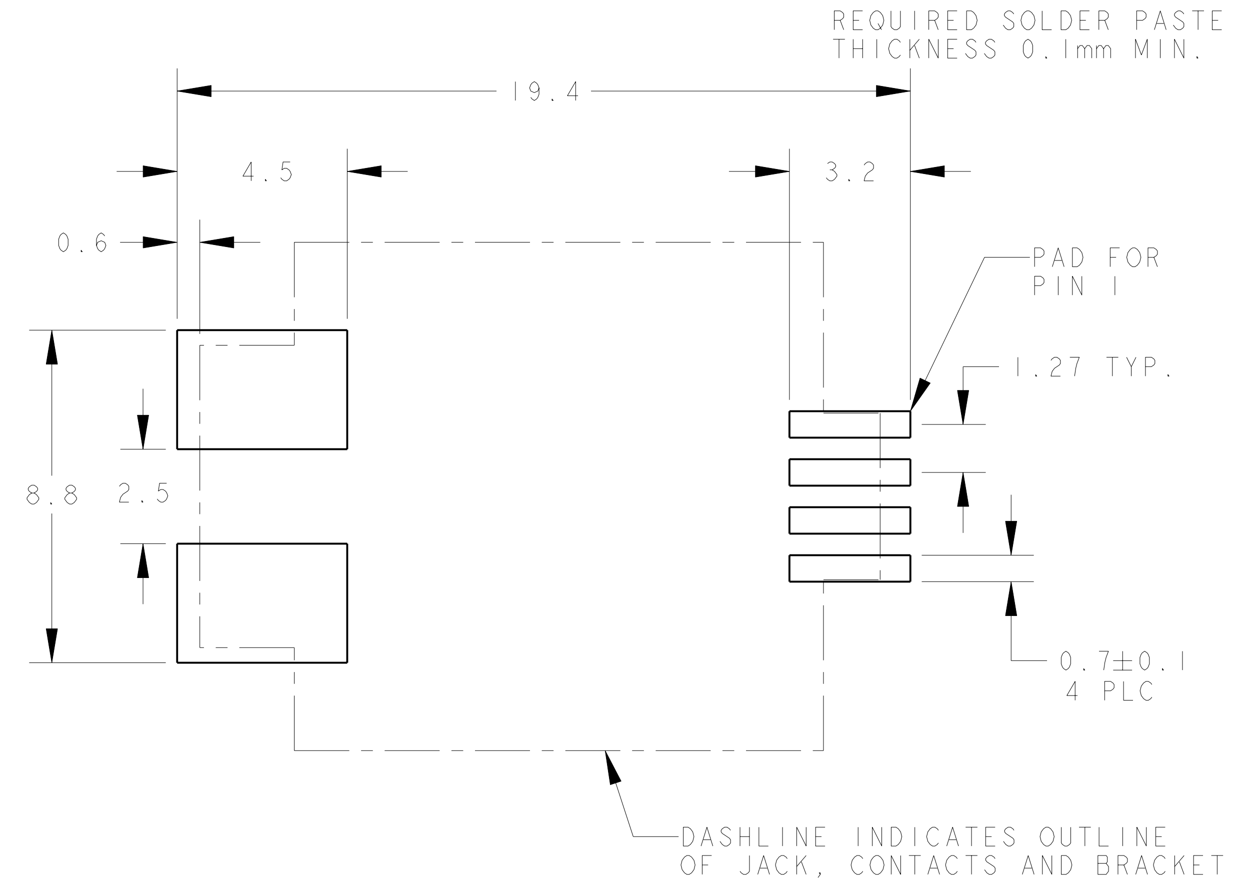
6 MEASURED AT HEEL OF CONTACTS
COPLANARITY AT TIPS OF CONTACTS MAX. 0.18mm

7 TAPE AND REEL PACKAGING ACCORDING TO EIA 481-3 SPECIFICATIONS.

8 INCLUDES KAPTON TAPE (10x11,5mm) ON TOP SURFACE AS PICK AND PLACE FEATURE.



PRINTED CIRCUIT BOARD LAYOUT (BOTTOM ENTRY APPL.)



PRINTED CIRCUIT BOARD LAYOUT (TOP ENTRY APPL.)

4 POS./4 CONT.	300 PCS ON Ø360 mm OD REEL. TOP ENTRY ORIENTATION PER DETAIL B	8 1982198-2
4 POS./4 CONT.	300 PCS ON Ø360 mm OD REEL. TOP ENTRY ORIENTATION PER DETAIL B	1982198-1
REMARKS	PACKAGING 7	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm

TOLERANCES UNLESS OTHERWISE SPECIFIED:
0 PLC ±-
1 PLC ±-
2 PLC ±-
3 PLC ±-
4 PLC ±-
ANGLES ±-

MATERIAL - SEE NOTE 3

FINISH - SEE NOTE 2

DWN VATHSA 18 Dec 2006
CHK PREMJITH 18 Dec 2006
APVD
PRODUCT SPEC 108-19117
APPLICATION SPEC 114-19041
WEIGHT -

CUSTOMER DRAWING

TE Connectivity

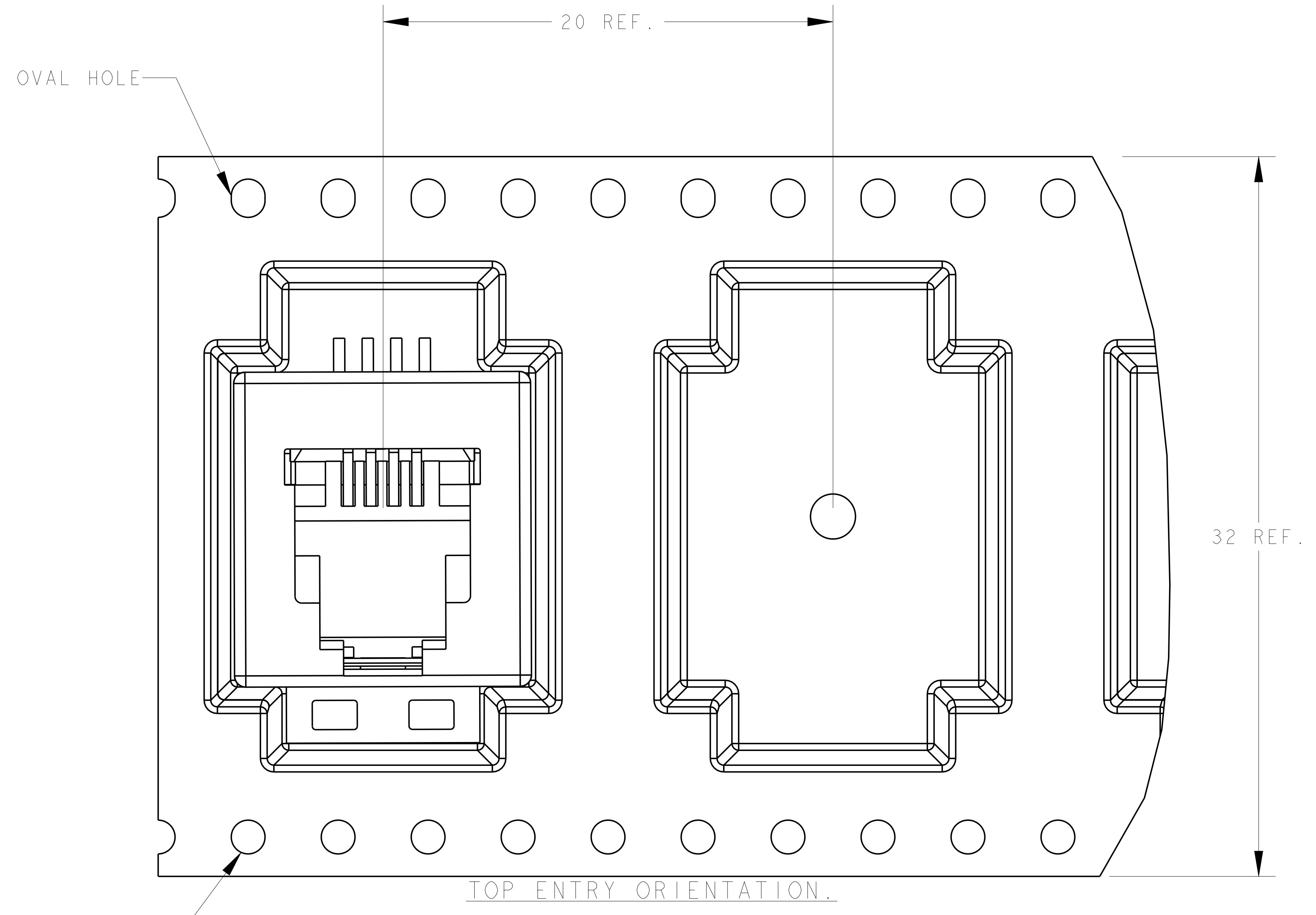
NAME
INVERTIBLE MODULAR JACK, 4 POSITION
HANDSET
FOR SURFACE MOUNT APPLICATION

SIZE A2
CAGE CODE
DRAWING NO C-1982198
RESTRICTED TO -
SCALE 5:1
SHEET 1 OF 2
REV C

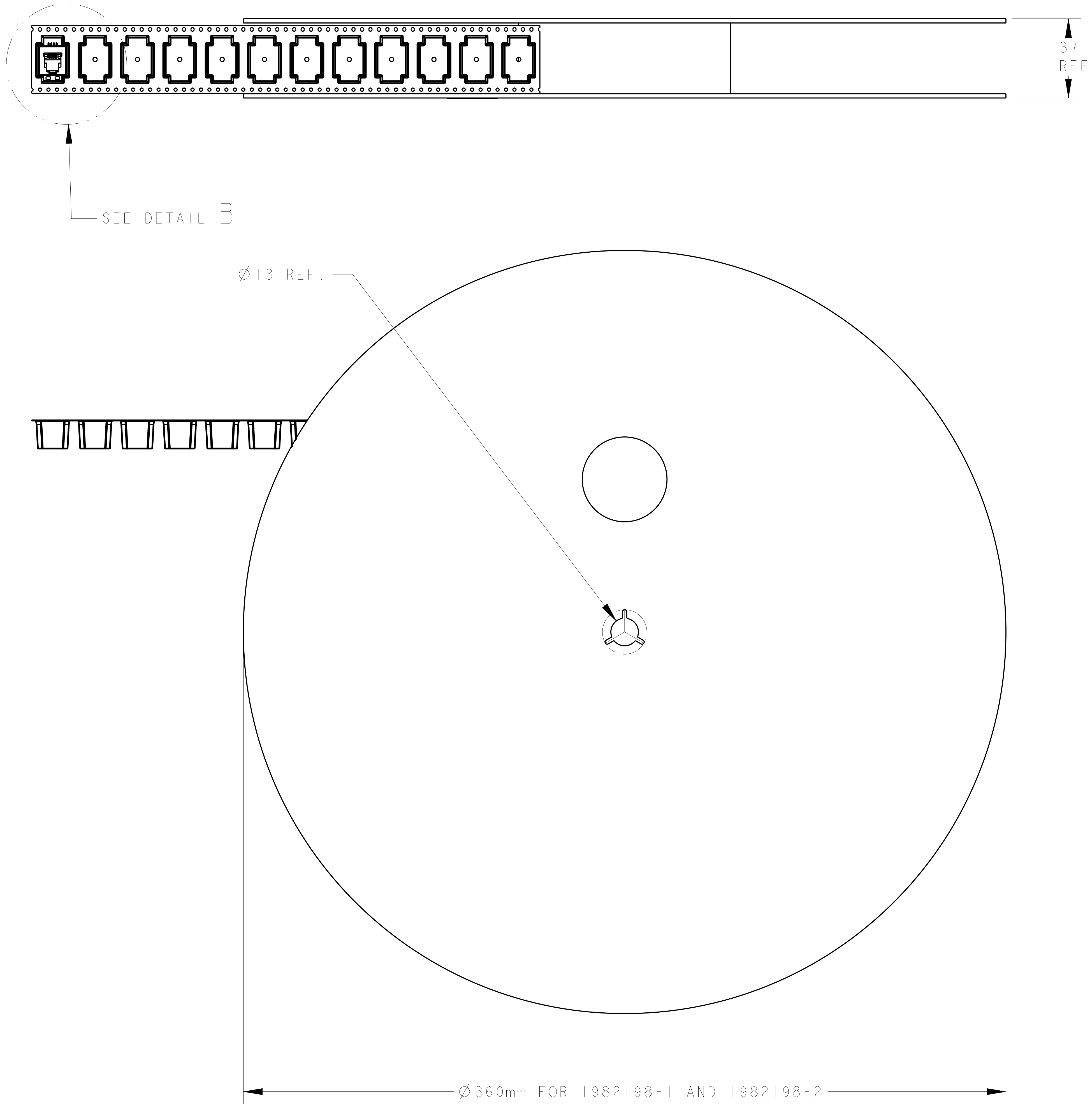
LOC	DIST
-	-

REVISIONS

P	LTR	DESCRIPTION	DATE	DWN	APVD
	-	SEE SHEET 1	-	-	-



DETAIL B
SCALE 4:1



THIS DRAWING IS A CONTROLLED DOCUMENT.

DWN Vathsa 18 Dec 06
CHK Premjith 18 Dec 06
APVD

DIMENSIONS: mm

TOLERANCES UNLESS OTHERWISE SPECIFIED:
0 PLC ± -
1 PLC ± -
2 PLC ± -
3 PLC ± -
4 PLC ± -
ANGLES ± -

MATERIAL -
FINISH -

PRODUCT SPEC 108-19117
APPLICATION SPEC 114-19041
WEIGHT -

TE Connectivity

NAME
INVERTIBLE MODULAR JACK, 4 POSITION
HANDSET
FOR SURFACE MOUNT APPLICATION

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A2		C- 1982198	-

CUSTOMER DRAWING

SCALE 5:1 SHEET 2 OF 2 REV C

C-1982198